



# STD8NM50N, STP8NM50N, STU8NM50N

N-channel 500 V, 0.73  $\Omega$  typ., 5 A MDmesh™II Power MOSFET in DPAK, TO-220 and IPAK packages

Datasheet — production data

## Features

Order codes	$V_{DSS}@T_{JMAX}$	$R_{DS(on)max.}$	$I_D$
STD8NM50N STP8NM50N STU8NM50N	550 V	< 0.79 $\Omega$	5 A

- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance

## Applications

- Switching applications

## Description

These devices are N-channel Power MOSFETs developed using the second generation of MDmesh™ technology. This revolutionary Power MOSFET associates a vertical structure to the company's strip layout to yield one of the world's lowest on-resistance and gate charge. It is therefore suitable for the most demanding high efficiency converters.

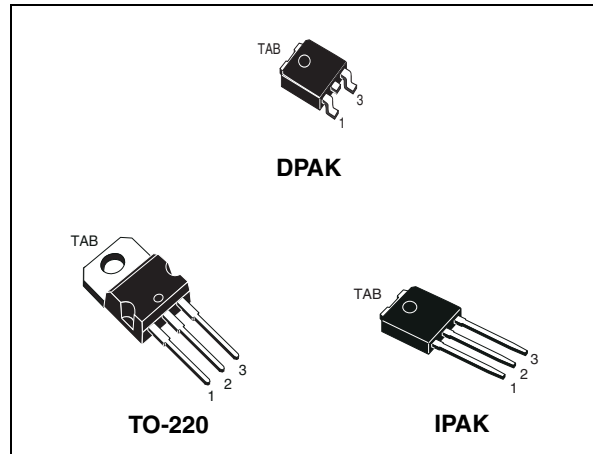


Figure 1. Internal schematic diagram

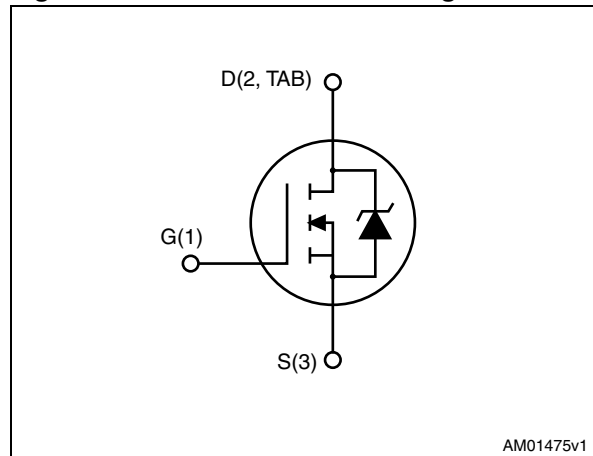


Table 1. Device summary

Order codes	Marking	Packages	Packaging
STD8NM50N	8NM50N	DPAK	Tape and reel
STP8NM50N		TO-220	Tube
STU8NM50N		IPAK	

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	500	V
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	5	A
$I_D$	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	3	A
$P_{TOT}$	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	45	W
$dv/dt^{(1)}$	Peak diode recovery voltage slope	15	V/ns
$T_{stg}$	Storage temperature	- 55 to 150	$^\circ\text{C}$
$T_j$	Max. operating junction temperature	150	$^\circ\text{C}$

1.  $I_{SD} \leq 7\text{ A}$ ,  $di/dt \leq 400\text{ A}/\mu\text{s}$ ,  $V_{Peak} < V_{(BR)DSS}$ ,  $V_{DS} = 80\% V_{(BR)DSS}$

**Table 3. Thermal data**

Symbol	Parameter	Value			Unit
		DPAK	IPAK	TO-220	
$R_{thj-case}$	Thermal resistance junction-case max	2.78			$^\circ\text{C}/\text{W}$
$R_{thj-amb}$	Thermal resistance junction-ambient max		100	62.5	$^\circ\text{C}/\text{W}$
$R_{thj-pcb}$	Thermal resistance junction-pcb max	50			$^\circ\text{C}/\text{W}$
$T_l$	Maximum lead temperature for soldering purpose		300		$^\circ\text{C}$

**Table 4. Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AR}$	Avalanche current, repetitive or not-repetitive (pulse width limited by $T_j$ max)	2	A
$E_{AS}$	Single pulse avalanche energy (starting $T_j = 25\text{ }^\circ\text{C}$ , $I_D = I_{AR}$ , $V_{DD} = 50\text{ V}$ )	140	mJ

## 2 Electrical characteristics

( $T_C = 25\text{ °C}$  unless otherwise specified)

**Table 5. On /off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage ( $V_{GS} = 0$ )	$I_D = 1\text{ mA}$	500			V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = 500\text{ V}$ $V_{DS} = 500\text{ V}, T_C = 125\text{ °C}$			1 100	$\mu\text{A}$ $\mu\text{A}$
$I_{GSS}$	Gate-body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 25\text{ V}$			$\pm 100$	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2	3	4	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}, I_D = 2.5\text{ A}$		0.73	0.79	$\Omega$

**Table 6. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 50\text{ V}, f = 1\text{ MHz},$ $V_{GS} = 0$	-	364	-	pF
$C_{oss}$	Output capacitance			33		pF
$C_{rss}$	Reverse transfer capacitance			1.2		pF
$C_{oss(eq)}^{(1)}$	Equivalent output capacitance time related	$V_{DS} = 0\text{ to }50\text{ V}, V_{GS} = 0$	-	147.5	-	pF
$R_G$	Intrinsic gate resistance	$f = 1\text{ MHz open drain}$	-	5.4	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 400\text{ V}, I_D = 5\text{ A},$ $V_{GS} = 10\text{ V}$ (see <a href="#">Figure 16</a> )	-	14	-	nC
$Q_{gs}$	Gate-source charge			3		nC
$Q_{gd}$	Gate-drain charge			7		nC

1.  $C_{oss\ eq}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$

**Table 7. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 250\text{ V}$ , $I_D = 5\text{ A}$ , $R_G = 4.7\ \Omega$ , $V_{GS} = 10\text{ V}$ (see <a href="#">Figure 15</a> )	-	7	-	ns
$t_r$	Rise time			4.4		ns
$t_{d(off)}$	Turn-off-delay time			25		ns
$t_f$	Fall time			8.8		ns

**Table 8. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		5	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				20	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 5\text{ A}$ , $V_{GS} = 0$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 5\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 60\text{ V}$ (see <a href="#">Figure 20</a> )	-	187		ns
$Q_{rr}$	Reverse recovery charge			1.3		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current			14		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 5\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 60\text{ V}$ , $T_J = 150\text{ }^\circ\text{C}$ (see <a href="#">Figure 20</a> )	-	224		ns
$Q_{rr}$	Reverse recovery charge			1.5		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current			13		A

1. Pulse width limited by safe operating area.

2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for DPAK and IPAК

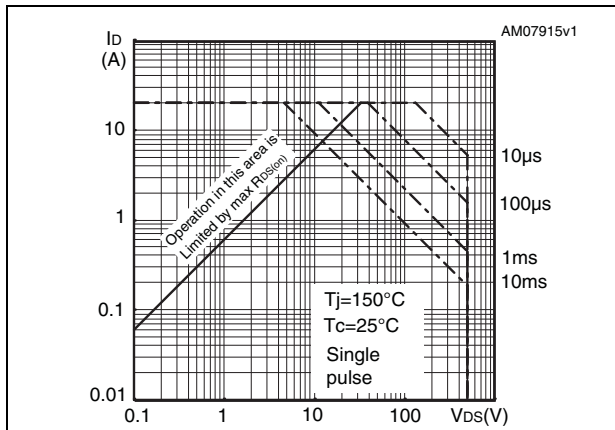


Figure 3. Thermal impedance for DPAK and IPAК

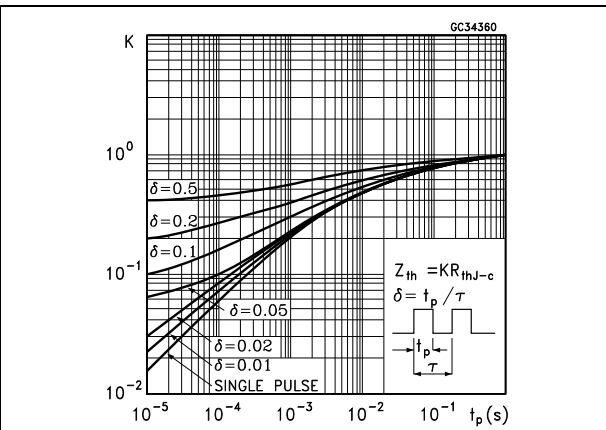


Figure 4. Safe operating area for TO-220

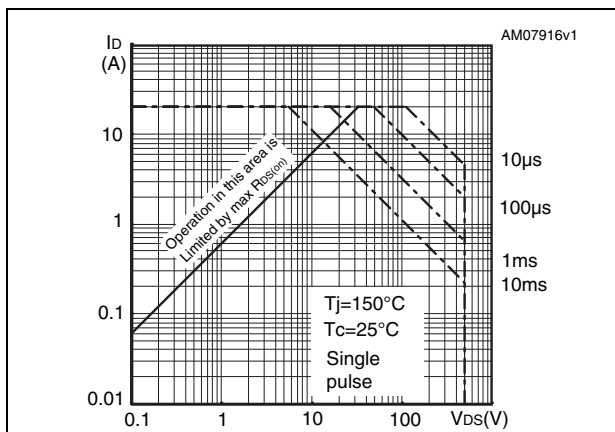


Figure 5. Thermal impedance for TO-220

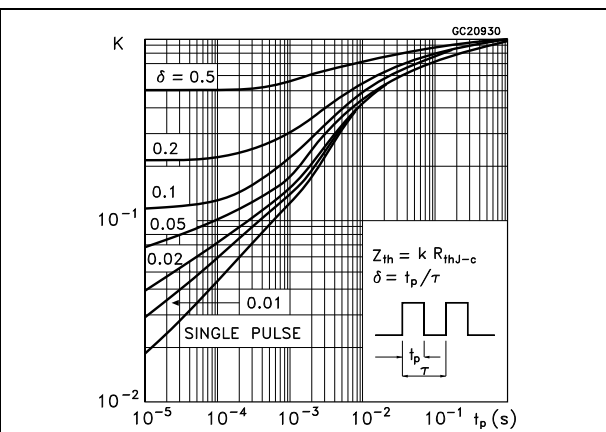


Figure 6. Output characteristics

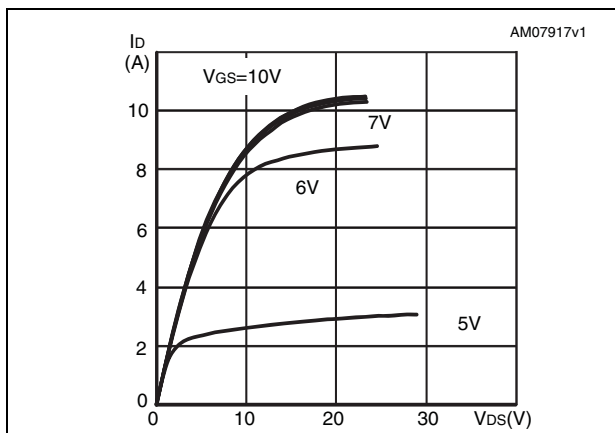


Figure 7. Transfer characteristics

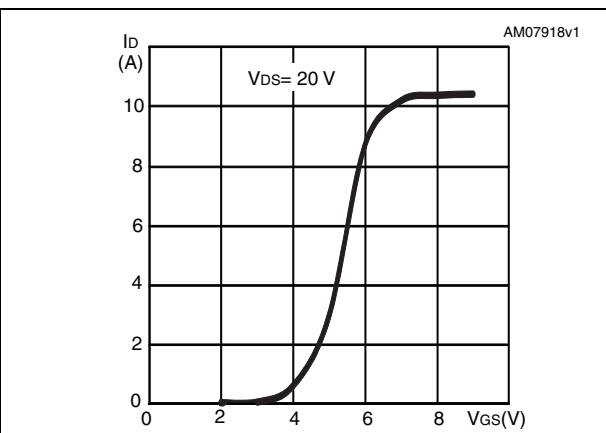


Figure 8. Static drain-source on resistance

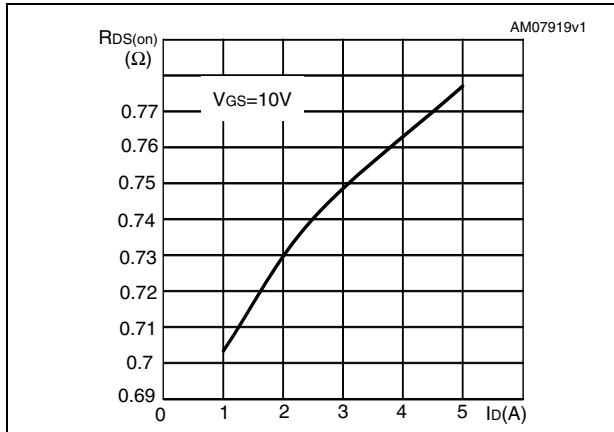


Figure 9. Gate charge vs gate-source voltage

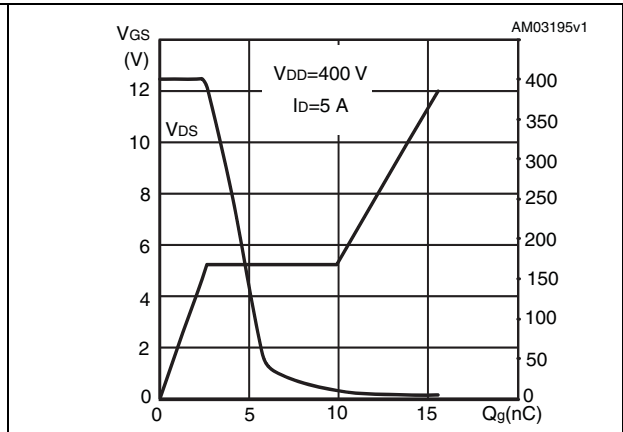


Figure 10. Capacitance variations

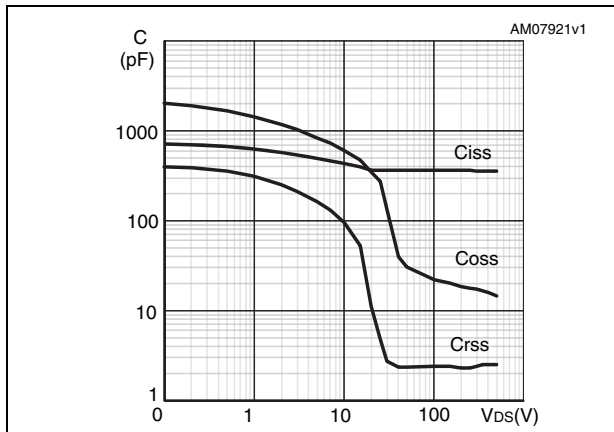


Figure 11. Output capacitance stored energy

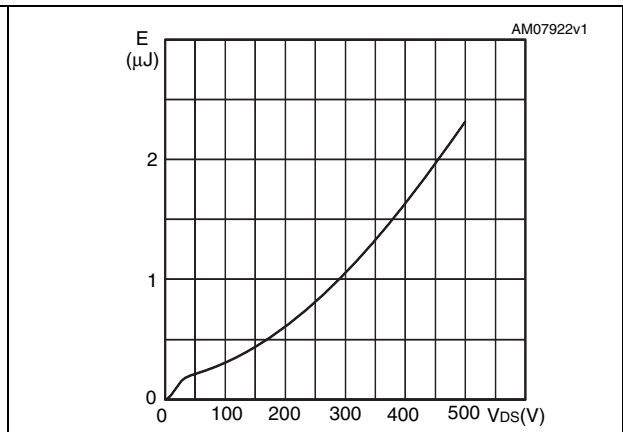


Figure 12. Normalized gate threshold voltage vs temperature

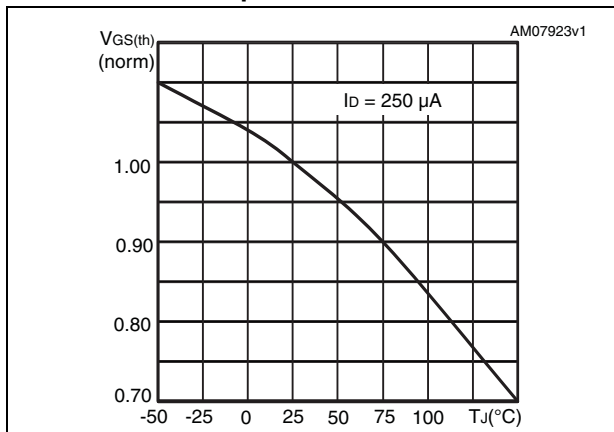


Figure 13. Normalized on resistance vs temperature

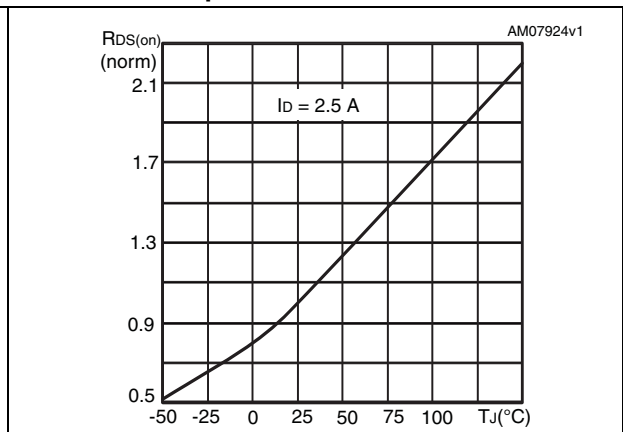
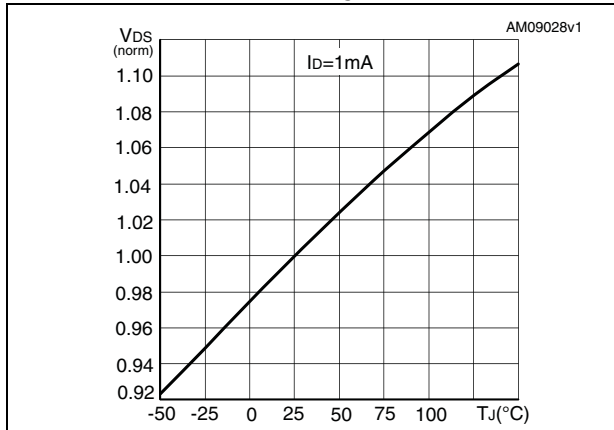


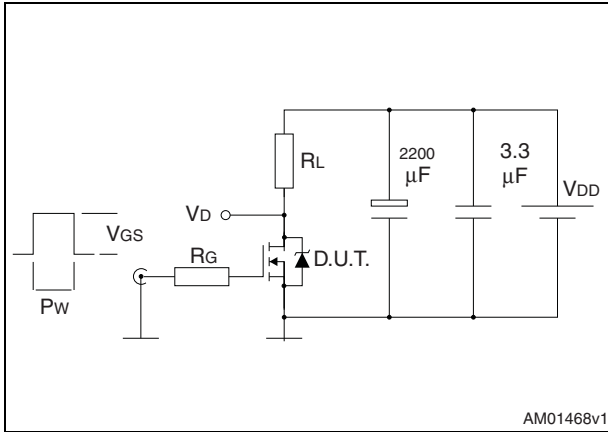
Figure 14. Normalized  $V_{DS}$  vs temperature



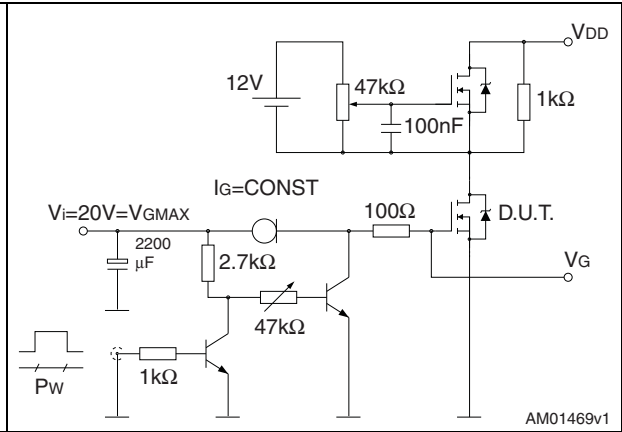


### 3 Test circuits

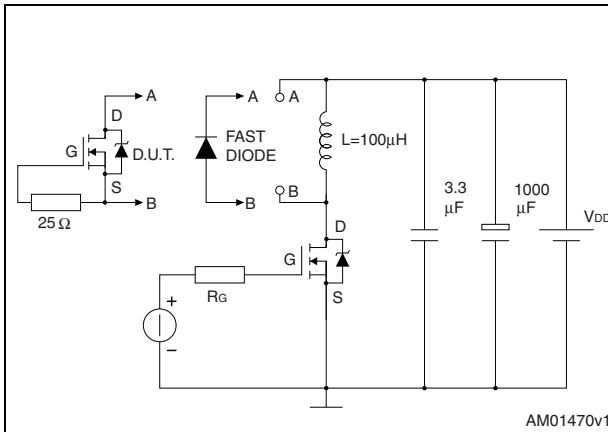
**Figure 15. Switching times test circuit for resistive load**



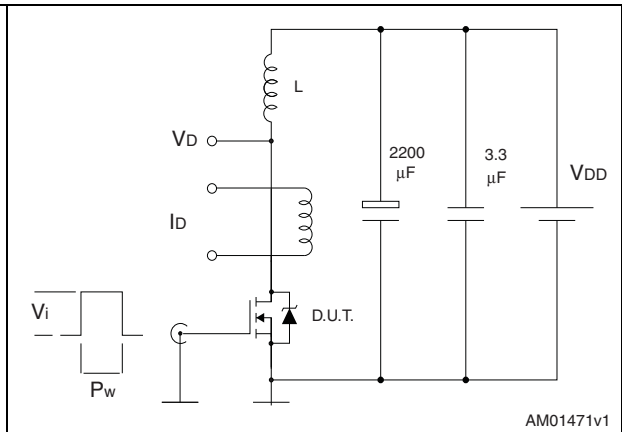
**Figure 16. Gate charge test circuit**



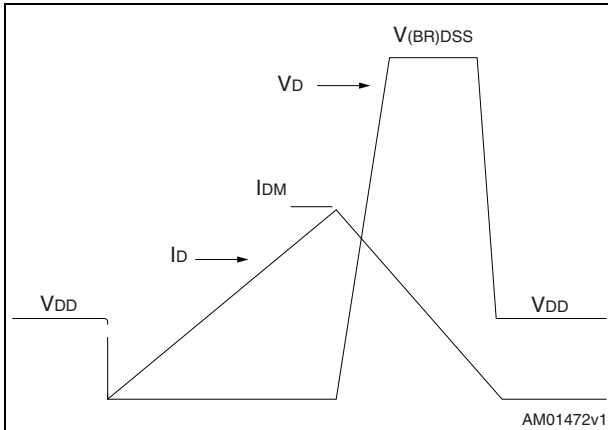
**Figure 17. Test circuit for inductive load switching and diode recovery times**



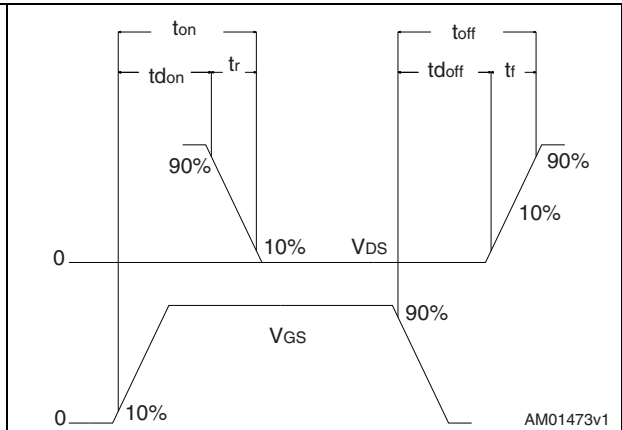
**Figure 18. Unclamped inductive load test circuit**



**Figure 19. Unclamped inductive waveform**



**Figure 20. Switching time waveform**



## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

**Table 9. DPAK (TO-252) mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1		5.10	
E	6.40		6.60
E1		4.70	
e		2.28	
e1	4.40		4.60
H	9.35		10.10
L	1		
L1		2.80	
L2		0.80	
L4	0.60		1
R		0.20	
V2	0°		8°

Figure 21. DPAK (TO-252) drawing

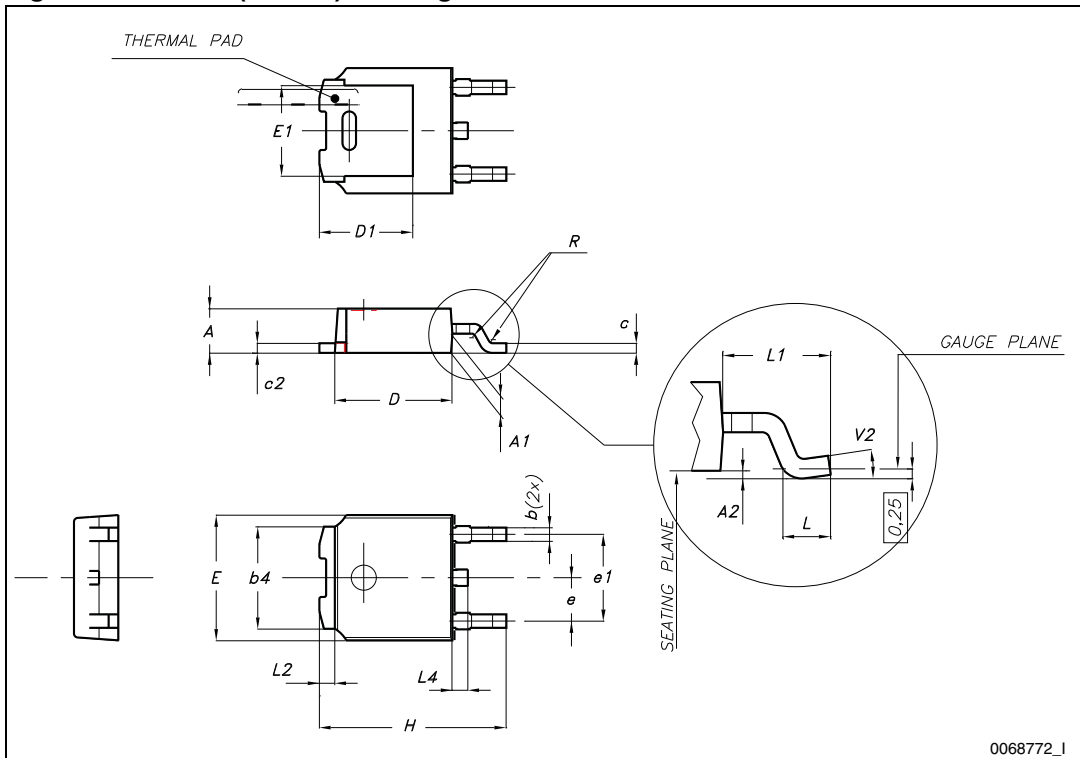
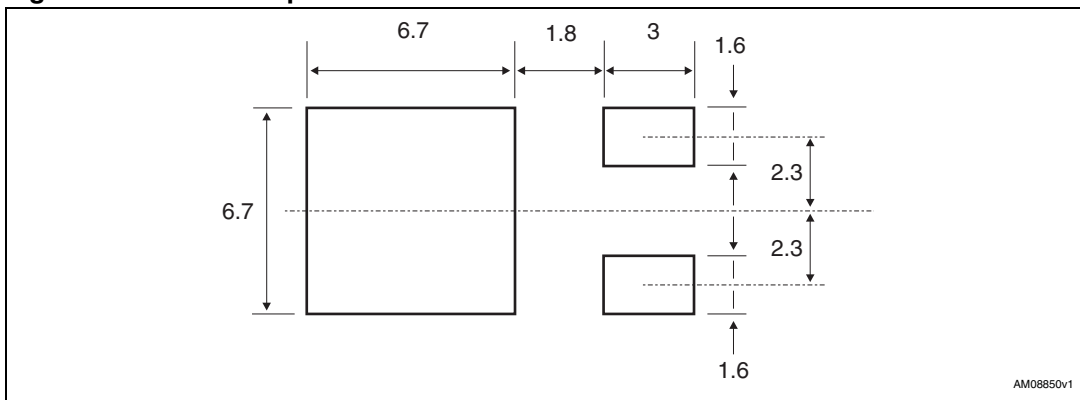


Figure 22. DPAK footprint<sup>(a)</sup>



a. All dimension are in millimeters

Table 10. TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

Figure 23. TO-220 type A drawing

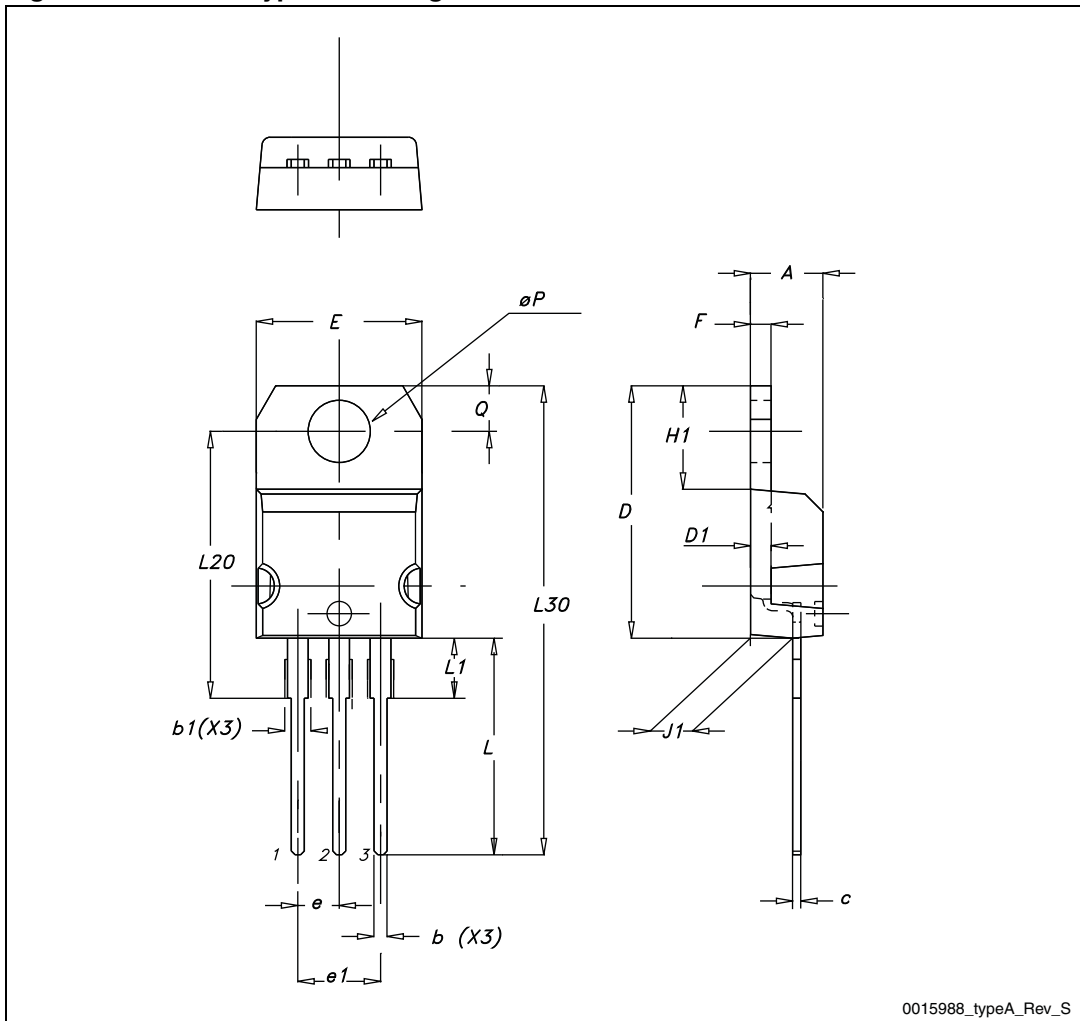
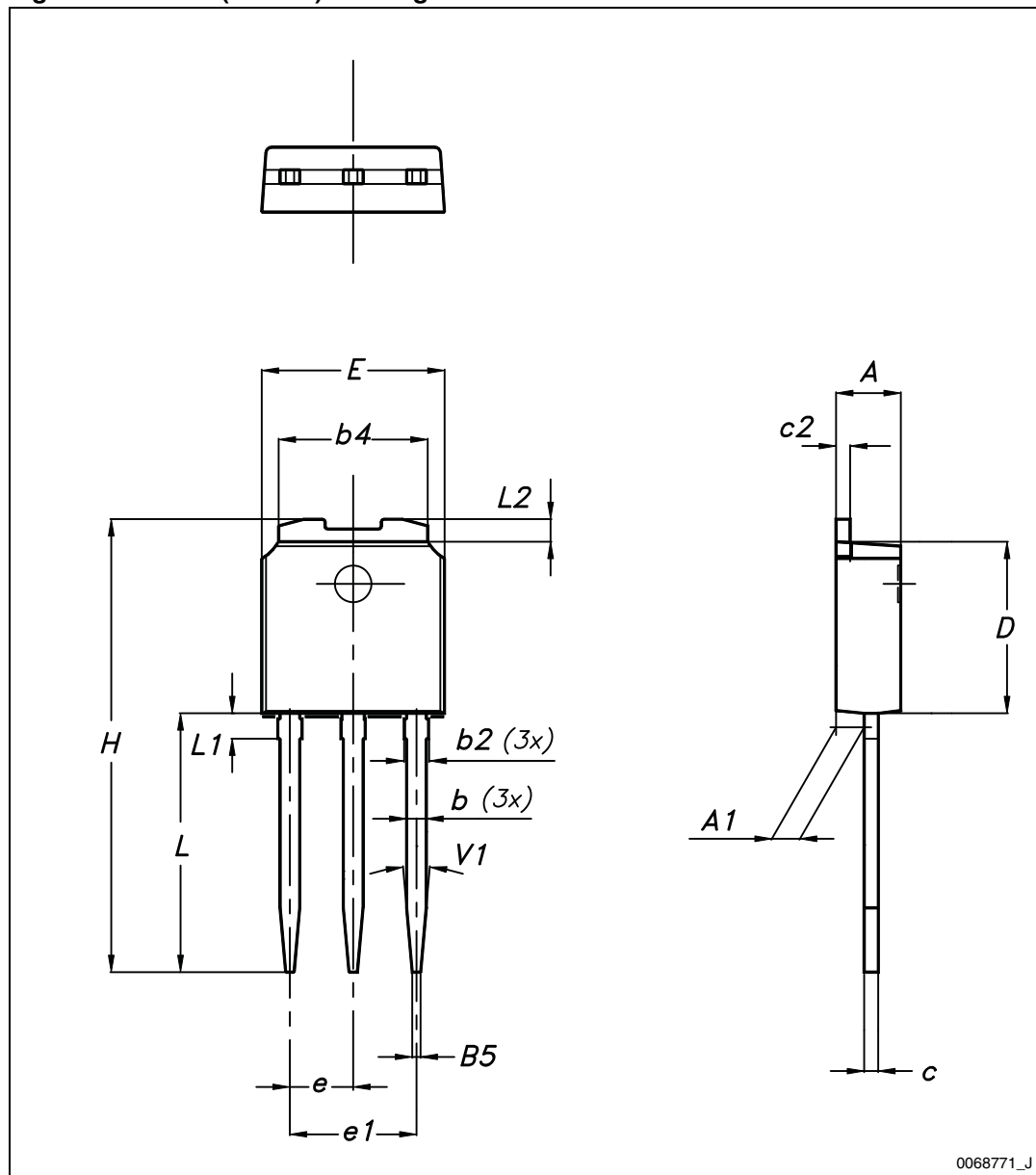


Table 11. IPAK (TO-251) mechanical data

DIM	mm.		
	min.	typ.	max.
A	2.20		2.40
A1	0.90		1.10
b	0.64		0.90
b2			0.95
b4	5.20		5.40
B5		0.30	
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
E	6.40		6.60
e		2.28	
e1	4.40		4.60
H		16.10	
L	9.00		9.40
L1	0.80		1.20
L2		0.80	1.00
V1		10°	

Figure 24. IPAK (TO-251) drawing



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## 5 Packaging mechanical data

Table 12. DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			



Figure 25. Tape for DPAK (TO-252)

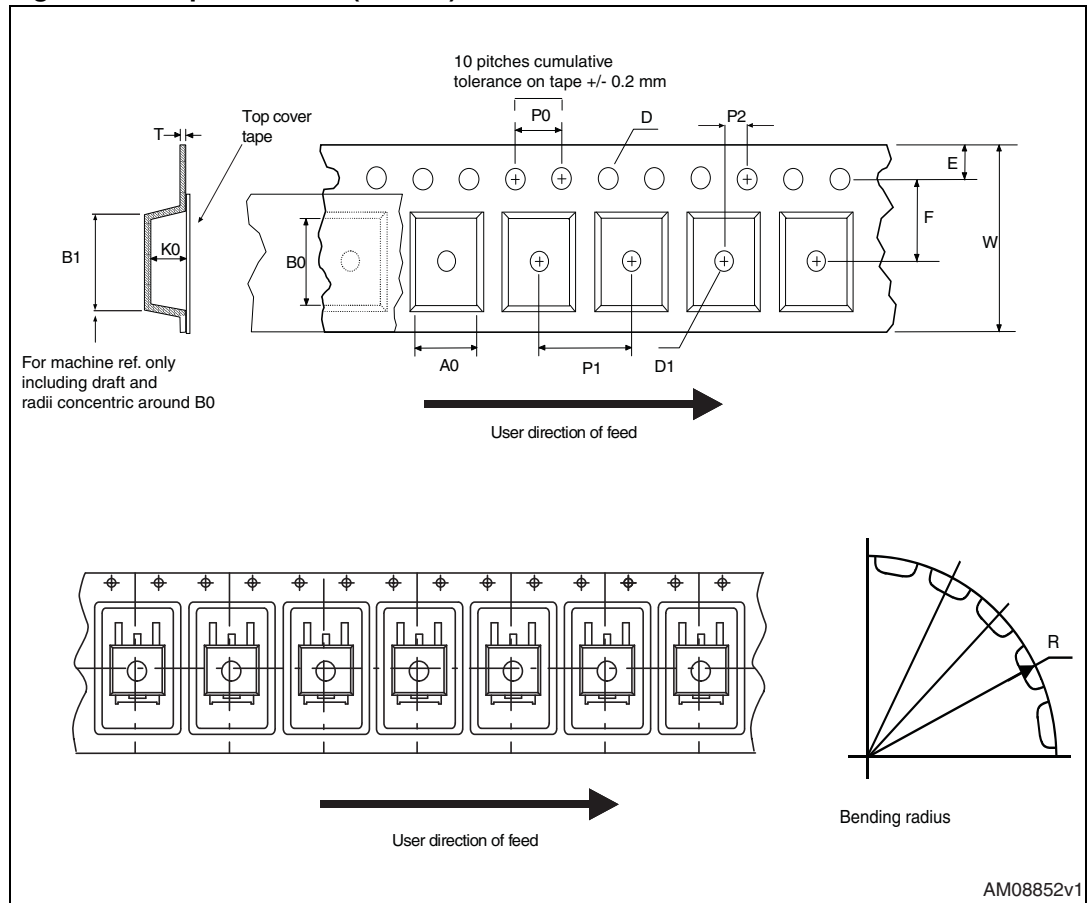
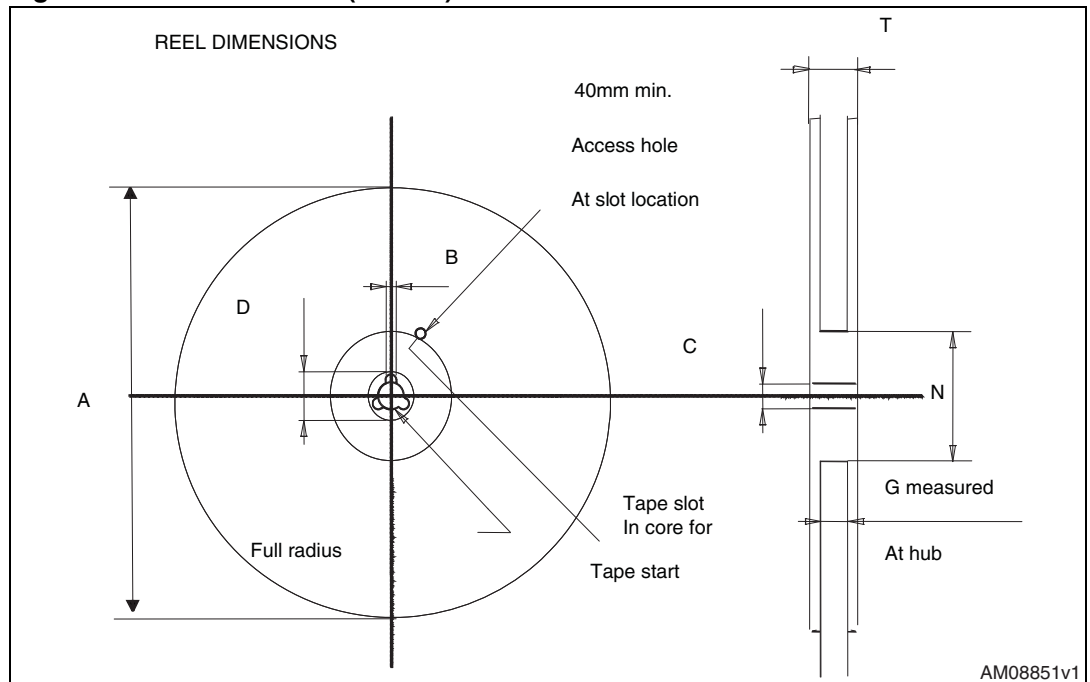


Figure 26. Reel for DPAK (TO-252)



## 6 Revision history

**Table 13. Document revision history**

Date	Revision	Changes
20-Apr-2010	1	First release.
03-Sep-2010	2	Document status promoted from preliminary data to datasheet. Inserted <a href="#">Section 2.1: Electrical characteristics (curves)</a> . Corrected $R_{DS(on)}$ max value in: <a href="#">Features</a> .
03-Feb-2011	3	Modified: <a href="#">Figure 4</a> . Modified: <a href="#">note 1</a> . Modified: <a href="#">Table 5</a> .
21-Oct-2011	4	Updated $V_{DSS}$ (@Tjmax) in cover page. Updated <a href="#">Section 4: Package mechanical data</a> . Minor text changes.
15-Nov-2011	5	The part number STF8NM50N has been moved to a separate datasheet.
13-Sep-2012	6	<a href="#">Figure 2</a> and <a href="#">Figure 4</a> have been modified. <a href="#">Section 4: Package mechanical data</a> has been updated.

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